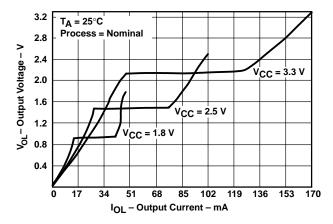
- Member of the Texas Instruments
   Widebus™ Family
- DOC™ (Dynamic Output Control) Circuit Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation
- Dynamic Drive Capability Is Equivalent to Standard Outputs With I<sub>OH</sub> and I<sub>OL</sub> of ±24 mA at 2.5-V V<sub>CC</sub>
- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II

### description

A Dynamic Output Control ( $DOC^{TM}$ ) circuit is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical  $V_{OL}$  vs  $I_{OL}$  and  $V_{OH}$  vs  $I_{OH}$  curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to TI application reports AVC Logic Family Technology and Applications, literature number SCEA006, and Dynamic Output Control ( $DOC^{TM}$ ) Circuitry Technology and Applications, literature number SCEA009.



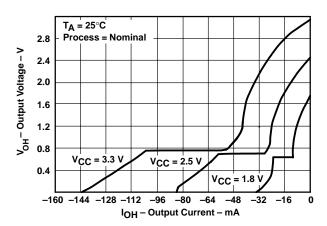


Figure 1. Output Voltage vs Output Current

This 18-bit universal bus driver is operational at 1.2-V to 3.6-V  $V_{CC}$ , but is designed specifically for 1.65-V to 3.6-V  $V_{CC}$  operation.

Data flow from A to Y is controlled by the output-enable ( $\overline{OE}$ ) input. The device operates in the transparent mode when the latch-enable (LE) input is high. The A data is latched if the clock (CLK) input is held at a high or low logic level. If LE is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLK. When  $\overline{OE}$  is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

DOC and Widebus are trademarks of Texas Instruments.



### terminal assignments

### **DGG OR DGV PACKAGE** (TOP VIEW)

	1		_		
NC	d	1	$\cup$	56	GND
NC		2		55	NC
Y1		3		54	] A1
GND	D	4		53	GND
Y2		5		52	] A2
Y3		6		51	] A3
$V_{CC}$		7		50	Vcc
Y4		8		49	] A4
Y5		9		48	] A5
Y6		10		47	] A6
GND	Ц	11		46	GND
Y7	Ц	12		45	] A7
Y8	Ц	13		44	8A [
Y9	Ц	14		43	A9
Y10		15		42	A10
Y11		16		41	A11
Y12	Ц	17		40	A12
GND	Ц	18		39	GND
Y13	Ц	19		38	] A13
Y14		20		37	A14
Y15	Ц	21		36	A15
$V_{CC}$	Ц	22		35	Vcc
Y16	Ц	23		34	A16
Y17	Ц	24		33	A17
GND		25		32	GND
Y18	$\Box$	26		31	A18
OE		27		30	CLK
LE	$\Box$	28		29	GND

NC - No internal connection

### **ORDERING INFORMATION**

TA	PACKAGE <sup>†</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	TSSOP – DGG	Tape and reel	SN74AVC16835DGGR	AVC16835
-40 C to 65 C	TVSOP - DGV	Tape and reel	SN74AVC16835DGVR	CVA835

<sup>†</sup>Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

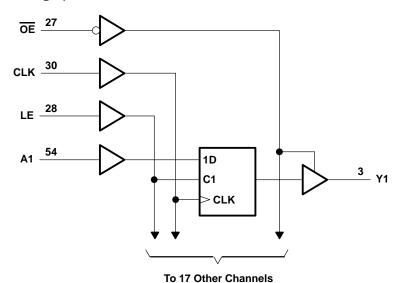


### **FUNCTION TABLE** (each universal bus driver)

	INF	PUTS		OUTPUT
OE	LE	CLK	Α	Υ
Н	Χ	Х	Χ	Z
L	Н	Χ	L	L
L	Н	Χ	Н	Н
L	L	$\uparrow$	L	L
L	L	$\uparrow$	Н	Н
L	L	L or H	Χ	Y <sub>0</sub> †

<sup>†</sup>Output level before the indicated steady-state input conditions were established, provided that CLK is high before LE goes low

### logic diagram (positive logic)





### SN74AVC16835 18-BIT UNIVERSAL BUS DRIVER WITH 3-STATE OUTPUTS

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 4.6 V
Input voltage range, V <sub>I</sub> (see Note 1)	
Voltage range applied to any output in the high-impedance or power-off state, VO	
(see Note 1)	–0.5 V to 4.6 V
Voltage range applied to any output in the high or low state, VO	
(see Notes 1 and 2)	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through each V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3): DGG package	64°C/W
DGV package	48°C/W
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vaa	Cupply voltage	Operating	1.4	3.6	V
VCC	Supply voltage	Data retention only	1.2		V
		V <sub>CC</sub> = 1.2 V	VCC		
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$	0.65 × V <sub>CC</sub>		
$V_{IH}$	High-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V <sub>CC</sub>		V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2		
		V <sub>CC</sub> = 1.2 V		GND	
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		$0.35 \times V_{CC}$	
$V_{IL}$	Low-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		0.8	
٧ <sub>I</sub>	Input voltage		0	3.6	V
۷o	Output voltage	Active state	0	VCC	V
٧O	Output voltage	3-state	0	3.6	V
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		-2	
lavia	Static high-level output current <sup>†</sup>	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		-4	mA
lohs	Static high-level output current	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-8	IIIA
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		-12	
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		2	
lo. o	Static low-level output current <sup>†</sup>	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		4	mA
lols	Static low-level output current	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		8	IIIA
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		12	
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 1.4 \text{ V to } 3.6 \text{ V}$		5	ns/V
TA	Operating free-air temperature		-40	85	°C

<sup>†</sup> Dynamic drive capability is equivalent to standard outputs with I<sub>OH</sub> and I<sub>OL</sub> of ±24 mA at 2.5-V V<sub>CC</sub>. See Figure 1 for V<sub>OL</sub> vs I<sub>OL</sub> and V<sub>OH</sub> vs I<sub>OH</sub> characteristics. Refer to TI application reports *AVC Logic Family Technology and Applications*, literature number **SCEA006**, and *Dynamic Output Control (DOC™) Circuitry Technology and Applications*, literature number **SCEA009**.

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to TI application report *Implications* of Slow or Floating CMOS Inputs, literature number SCBA004.



### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CO	NDITIONS	Vcc	MIN	TYP <sup>†</sup>	MAX	UNIT	
		$I_{OHS} = -100  \mu A$ ,		1.4 V to 3.6 V	V <sub>CC</sub> -0.	2			
		$I_{OHS} = -2 \text{ mA},$	V <sub>IH</sub> = 0.91 V	1.4 V	1.05				
Vон		$I_{OHS} = -4 \text{ mA},$	V <sub>IH</sub> = 1.07 V	1.65 V	1.2			V	
		$I_{OHS} = -8 \text{ mA},$	V <sub>IH</sub> = 1.7 V	2.3 V	1.75				
		$I_{OHS} = -12 \text{ mA},$	V <sub>IH</sub> = 2 V	3 V	2.3				
		$I_{OLS} = 100 \mu A$		1.4 V to 3.6 V			0.2		
		$I_{OLS} = 2 \text{ mA},$	V <sub>IL</sub> = 0.49 V	1.4 V			0.4		
VOL		$I_{OLS} = 4 \text{ mA},$	$V_{IL} = 0.57 V$	1.65 V			0.45	V	
		$I_{OLS} = 8 \text{ mA},$	$V_{IL} = 0.7 V$	2.3 V			0.55		
		$I_{OLS} = 12 \text{ mA},$	$V_{IL} = 0.8 V$	3 V			0.7		
П		$V_I = V_{CC}$ or GND		3.6 V			±2.5	μΑ	
I <sub>off</sub>		$V_I$ or $V_O = 3.6 V$		0			±10	μΑ	
loz		$V_O = V_{CC}$ or GND,	OE = V <sub>CC</sub>	3.6 V			±10	μΑ	
ICC		$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			40	μΑ	
	CLK input	V <sub>I</sub> = V <sub>CC</sub> or GND		2.5 V		4			
	OLK IIIput	Al = ACC or QIAD		3.3 V		4			
Ci	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND		2.5 V		4		pF	
<sup>C</sup>	Control inputs	AL = ACC OLGIAD		3.3 V		4		ρı	
	Data inputs	V <sub>I</sub> = V <sub>CC</sub> or GND		2.5 V		2.5			
	Data Iriputs	AL = ACC OLGIAD		3.3 V		2.5			
	C Outpute	Vo = Voo or GND		2.5 V		6.5	nF.		
Co	Outputs	$V_O = V_{CC}$ or GND		3.3 V		6.5		pF	

<sup>†</sup> Typical values are measured at  $T_A = 25$ °C.

# timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 2 through 5)

			V <sub>CC</sub> = 1.2 V		V <sub>CC</sub> = 1.5 V ± 0.1 V		V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT		
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
fclock	f <sub>clock</sub> Clock frequency							150		150		150	MHz		
	Pulse	LE high	LE high					3.3		3.3		3.3		ns	
t <sub>W</sub>	duration CLK high or low						3.3		3.3		3.3		115		
	•	Data before (	CLK <sup>↑</sup>	1		0.9		0.7		0.7		0.7			
t <sub>su</sub>	Setup time	Data	CLK high	1.7		1.6		1.2		0.8		0.8		ns	
	unio	before LE↓	CLK low	2		0.9		0.7		0.5		0.5			
		Data after CLK↑		1.5		1.3		1		0.9		1.3			
t <sub>h</sub>	Hold time	Data	CLK high	3.2		2.4		2		1.7		1.6		ns	
	unie	after LE↓	CLK low	2.8		2.1		1.7		1.5		1.4			

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# switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 2 through 5)

PARAMETER FROM (INPUT)		TO (OUTPUT)	V <sub>CC</sub> = 1.2 V	V <sub>CC</sub> =		V <sub>CC</sub> = ± 0.1		V <sub>CC</sub> =		V <sub>CC</sub> =		UNIT
	(1141 01)	(0011-01)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	1 1
f <sub>max</sub>						150		150		150		MHz
	Α		4.5	1.2	6.2	1.3	5.5	1	3.1	0.9	2.5	
<sup>t</sup> pd	LE	Y	6.2	1.6	9.4	1.3	7.2	1.1	4.7	0.9	3.8	ns
	CLK		5.2	1.6	7.8	1.5	6	1	3.7	0.8	3.1	
t <sub>en</sub>	ŌĒ	Υ	7.1	2.4	10.2	2.2	8.8	1.5	6.7	1.2	6.2	ns
t <sub>dis</sub>	ŌĒ	Y	6.9	2.2	10.3	2	8.4	1.2	5.3	1.1	5.3	ns

## switching characteristics, $T_A = 0$ °C to 85°C, $C_L = 0$ pF<sup>†</sup>

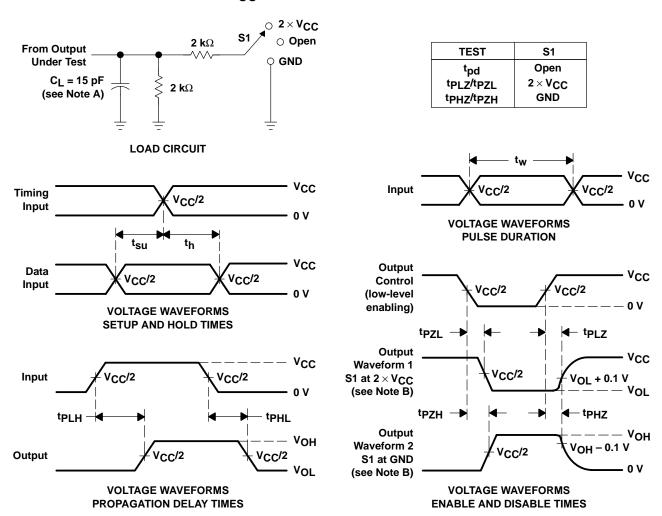
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = ± 0.1	UNIT	
	(1141 01)	(6611 61)	MIN	MAX	
• .	А	V	0.6	1.3	no
ιpd	CLK	Ţ	0.7	1.5	ns

<sup>†</sup> Texas Instruments SPICE simulation data

### operating characteristics, T<sub>A</sub> = 25°C

	PARAMETER	TEST CONDITION	)NG	V <sub>CC</sub> = 1.8 V	= 1.8 V   V <sub>CC</sub> = 2.5 V   V <sub>CC</sub> = 3.3 V		UNIT		
PARAMETER		TEST CONDITIO	JNS	TYP	TYP	TYP	ONIT		
	Power dissipation	Outputs enabled	C: 0 f 10	N/I I	45	48	52	٠,	
Cpd	capacitance	Outputs disabled	$C_L = 0, \qquad f = 10$	IVITZ	23	25	28	pF	

# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.2 \text{ V}$ AND 1.5 V $\pm$ 0.1 V



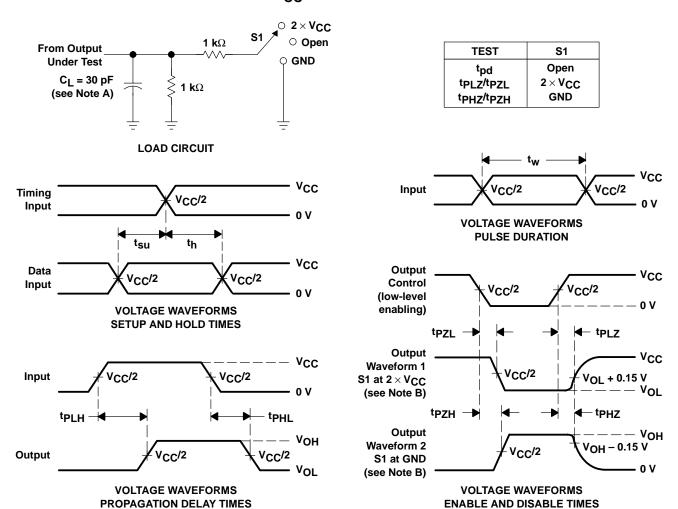
NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 2$  ns.  $t_f \leq 2$  ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



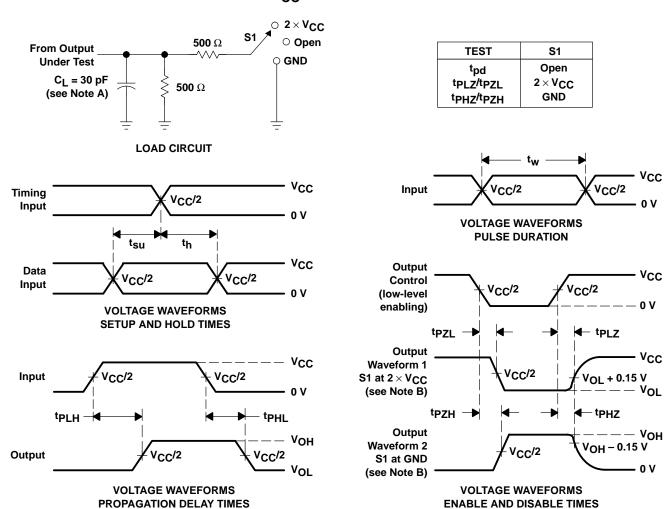
# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$



- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 2$  ns,  $t_f \leq 2$  ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. tpLZ and tpHZ are the same as tdis.
  - F. tpzL and tpzH are the same as ten.
  - G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms

# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$

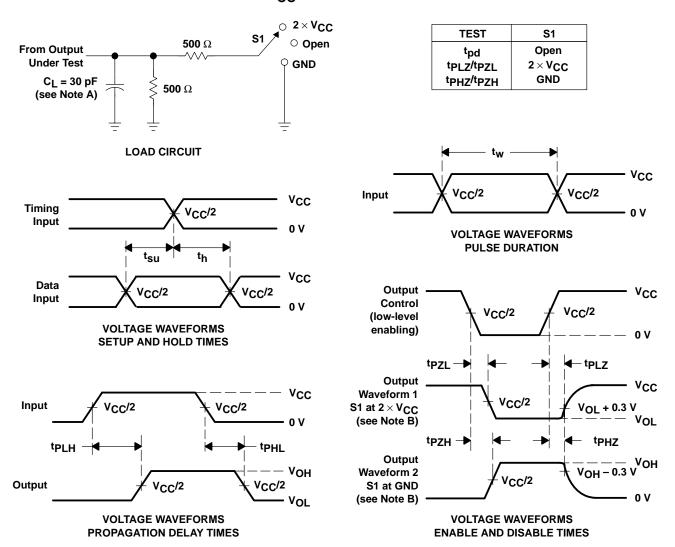


- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq$  2 ns,  $t_f \leq$  2 ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. tpLZ and tpHZ are the same as tdis.
  - F. tpzL and tpzH are the same as ten.
  - G. tpLH and tpHL are the same as tpd.

Figure 4. Load Circuit and Voltage Waveforms



# PARAMETER MEASUREMENT INFORMATION $V_{CC}$ = 3.3 V $\pm$ 0.3 V



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 2$  ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G. tpLH and tpHL are the same as tpd.

Figure 5. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74AVC16835DGVR	Active	Production	TVSOP (DGV)   56	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CVA835
SN74AVC16835DGVR.B	Active	Production	TVSOP (DGV)   56	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CVA835

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

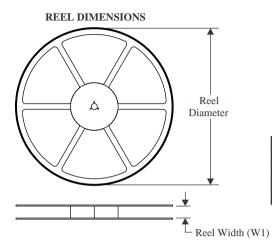
<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

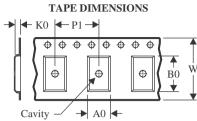
<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

### **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

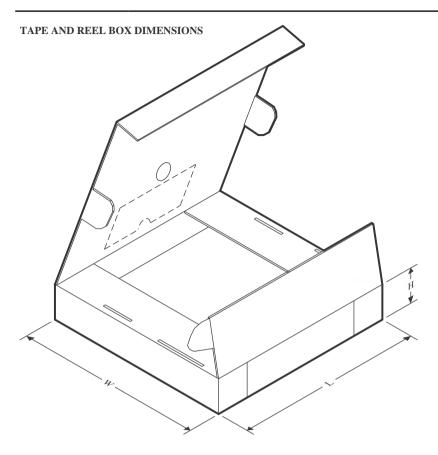


#### \*All dimensions are nominal

	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	` '	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ı	SN74AVC16835DGVR	TVSOP	DGV	56	2000	330.0	24.4	6.8	11.7	1.6	12.0	24.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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### \*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	SN74AVC16835DGVR	TVSOP	DGV	56	2000	356.0	356.0	45.0	

### DGV (R-PDSO-G\*\*)

### 24 PINS SHOWN

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

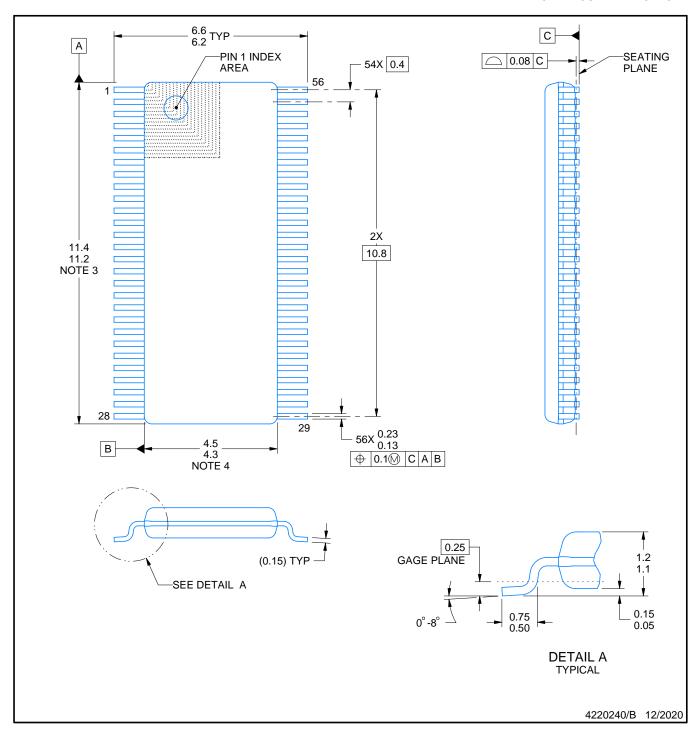
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



SMALL OUTLINE PACKAGE



#### NOTES:

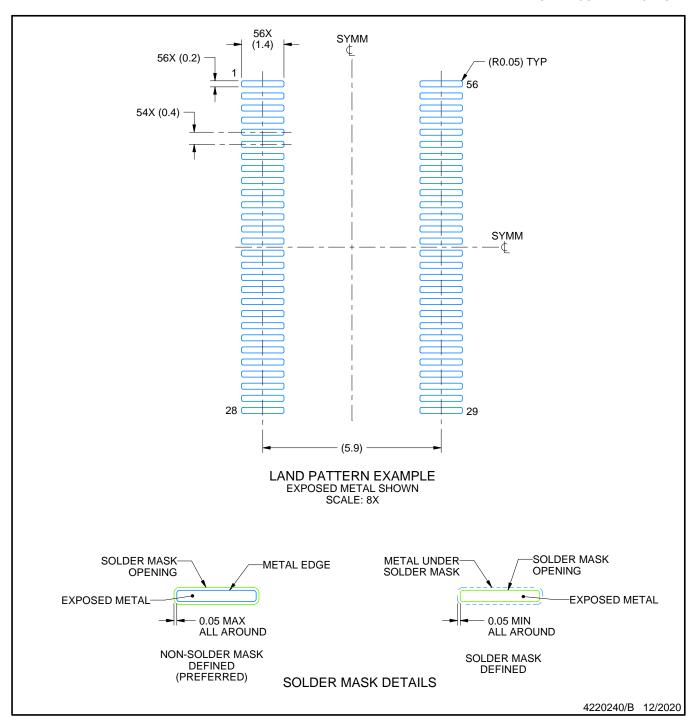
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-194.



SMALL OUTLINE PACKAGE



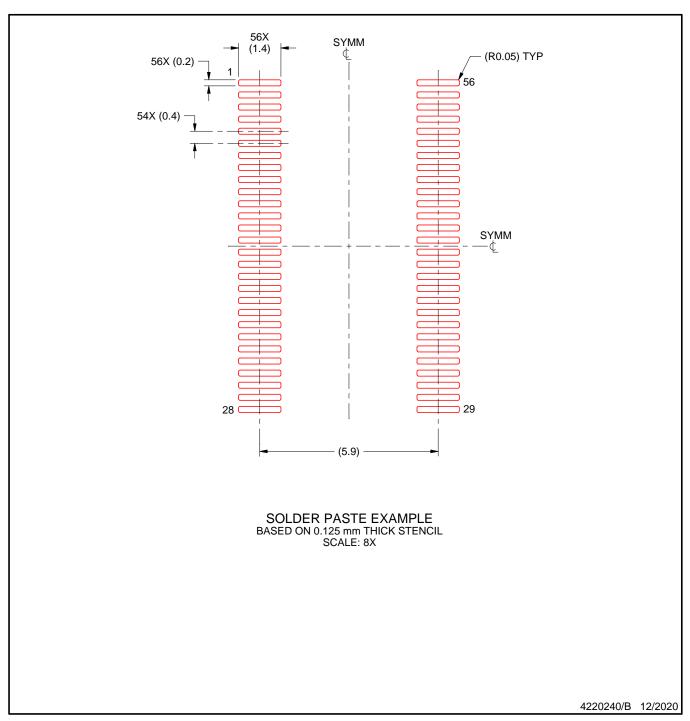
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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